General Purpose ABS, POLYLAC® PA-756H

Processing Conditions

A. Pre-drying  80 ~ 85 °C x 2 ~ 4 hrs depending on
   a) Humidity
   b) Ratio of reground resin
   c) Storage conditions

B. Barrel Setting Profile

   MAX (°C)  230
   MIN (°C)  190

C. Mold Temperature  30~70°C depending on
   a) Thickness
   b) Dimension
   c) Gate and runner system

NOTE:
1. Keep the resin from dust and contamination during handling and production.
2. Do not retain the hot melt at the barrel for a long time between injection cycles.
3. Temperature setting of manifold system should not exceed 240°C to avoid melt from degraded.

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